



Material Content Data Sheet



Sales Product Name		ESD307-U1-02N E6327		Issued		19. July 2018		
MA#		MA001212982						
Package		PG-TSNP-2-2		Weight*		1.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.105	5.58	5.58	55764	55764
leadframe	non noble metal	copper	7440-50-8	0.974	51.72		517186	
		chromium	7440-47-3	0.003	0.16		1563	
		zinc	7440-66-6	0.002	0.10		1042	
	non noble metal	tin	7440-31-5	0.002	0.13	52.11	1303	521094
		copper	7440-50-8	0.007	0.35	0.35	3463	3463
		silicondioxide	60676-86-0	0.553	29.35		293513	
encapsulation	organic material	carbon black	1333-86-4	0.003	0.17		1726	
		plastics	epoxy resin	-	0.094	5.01	34.53	50070
leadfinish	non noble metal	tin	7440-31-5	0.055	2.90	2.90	29000	29000
plating	noble metal	silver	7440-22-4	0.022	1.17	1.17	11692	11692
glue	noble metal	silver	7440-22-4	0.051	2.69		26943	
		plastics	epoxy resin	-	0.013	0.67	3.36	6735
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com